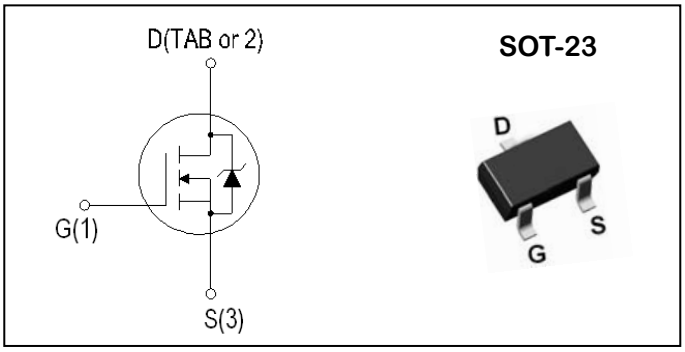
N-Channel Enhancement Mode Field Effect Transistor



PRODUCT SUMMARY

V_{DSS}	I_D	$R_{DS(ON)}$ (mΩ)
20V	4.2A	18mΩ

Absolute Maximum Ratings (T_A = 25°C unless otherwise specifed)

Symbol	Parameter		Ratings	Unit
Common Ratings				
V_{DSS}	Drain-Source Voltage		20	V
V_{GSS}	Gate-Source Voltage		±12	
T_J	Maximum Junction Temperature		125	°C
T_{STG}	Storage Temperature Range		-55 to 150	°C
I_S	Diode Continuous Forward Current（3）	TC=25°C	1.25	A
Mounted on Large Heat Sink				
I_{DM}	300μs Pulse Drain Current Tested(1)	T_C=25°C	12	A
I_D	Continuous Drain Current	T_C=25°C	4.6	A
		T_C=125°C	4.2	A
P_D	Maximum Power Dissipation（3）		1.25	W

1. Pulse width limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
R_{thJA}	Thermal resistance junction-ambient max（3）	100	°C/W

Electrical Characteristics (TA=25°C Unless Otherwise Noted)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
On/off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_{DS}=250uA	20	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}= 16V, V_{GS}=0V	--	--	1	uA
		V_{DS}=16V, V_{GS}=0V T_J=55°C	--	--	10	
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=250uA	0.5	0.8	1.5	V
I_{GSS}	Gate Leakage Current	V_{GS}=±8V, V_{DS}=0V	--	--	±100	nA
$R_{DS(ON)}$	Drain-SourceOn-stateResistance(2)	V_{GS}= 10V, I_{DS}=2.8A	--	18	21	mΩ
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{GS}=0V,	--	608	--	pF
C_{oss}	Output Capacitance	V_{DS}= 10V,	--	115	--	
C_{rss}	Reverse Transfer Capacitance	Frequency=1.0MHz	--	86	--	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time(1)	V_{DD}=10V,	--	10	--	ns
t_r	Turn-on Rise Time(1)	I_D= 3.6A, V_{GS}= 4.5V,	--	14	--	
$t_{d(OFF)}$	Turn-off Delay Time(1)	R_{GEN}=10Ω	--	39	--	
t_f	Turn-off Fall Time(1)		--	26	--	
Q_g	Total Gate Charge(1)	V_{DS}=10V, V_{GS}= 4.5V,	--	9.2	--	nC
Q_{gs}	Gate-Source Charge(1)	I_{DS}=1A	--	1.6	--	
Q_{gd}	Gate-Drain Charge(1)		--	2.6	--	
Diode Characteristics						
V_{SD}	Diode Forward Voltage(2)	I_{SD} = 1.25A, V_{GS} = 0	--	0.84	1.3	V

NOTES:

1. Independent of operating temperature.
2. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%
3. Surface Mounted on FR4 Board, t < 10 sec.

Typical Performance Characteristics

Figure 1: Output Characteristics

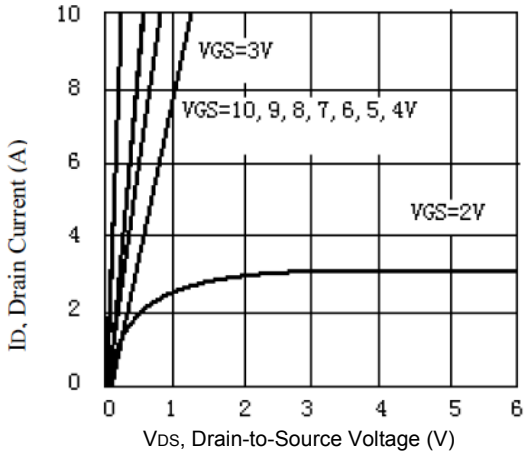


Figure 2: Transfer Characteristics

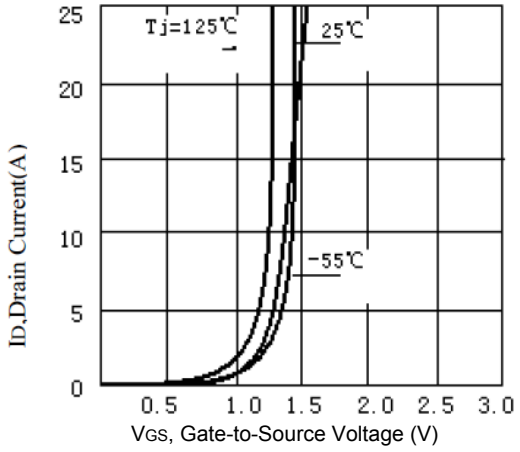


Figure 3: Gate Threshold Variation with Temperature

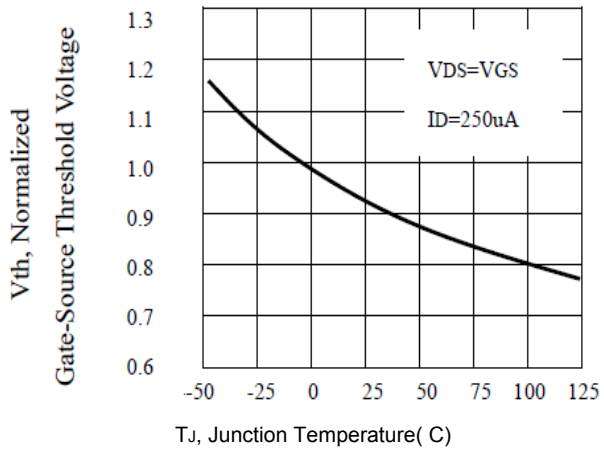


Figure 4: On-Resistance Variation with Temperature

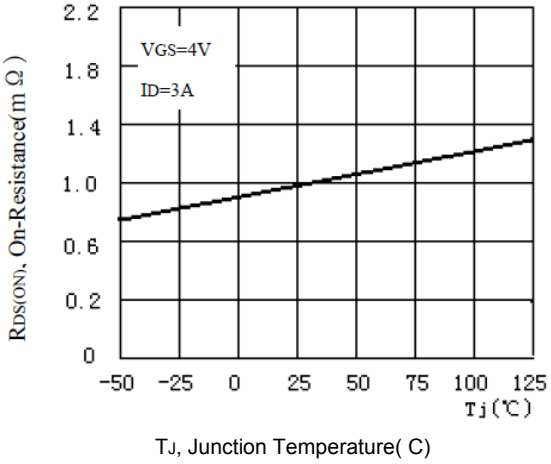


Figure 5: Capacitance Characteristics

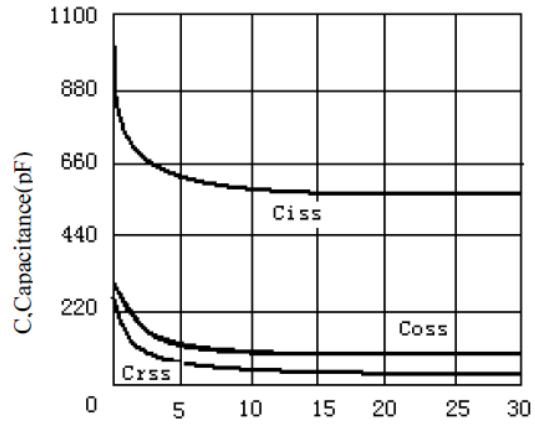


Figure 6: Body Diode Forward Voltage Variation with Source Current

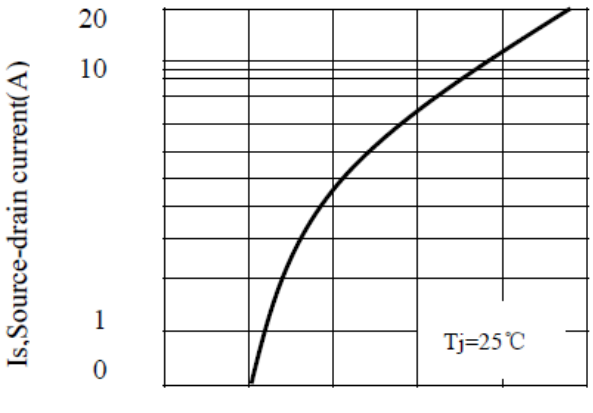


Figure 7: Gate Charge

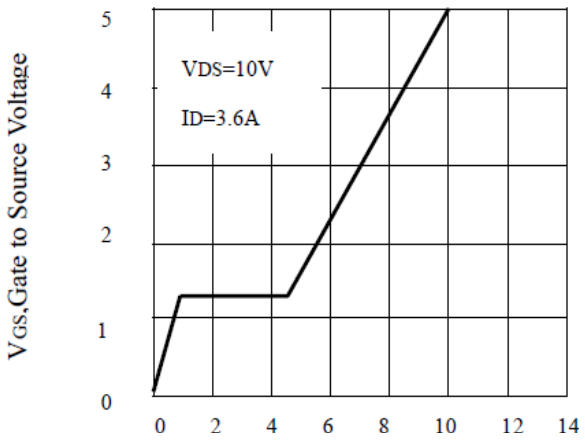


Figure 8: Maximum Safe Operating Area

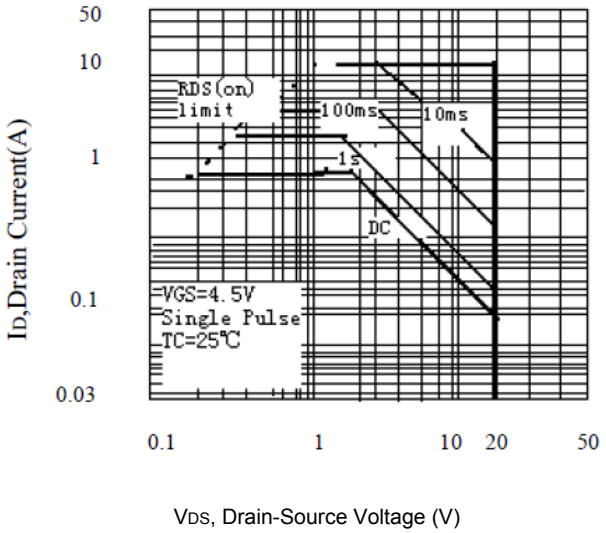
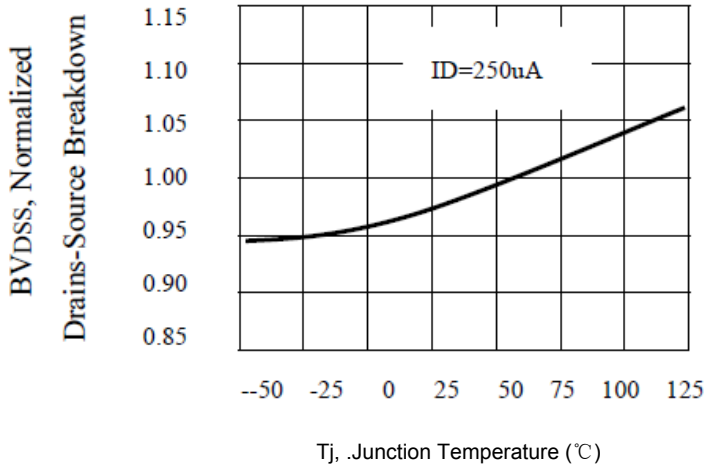
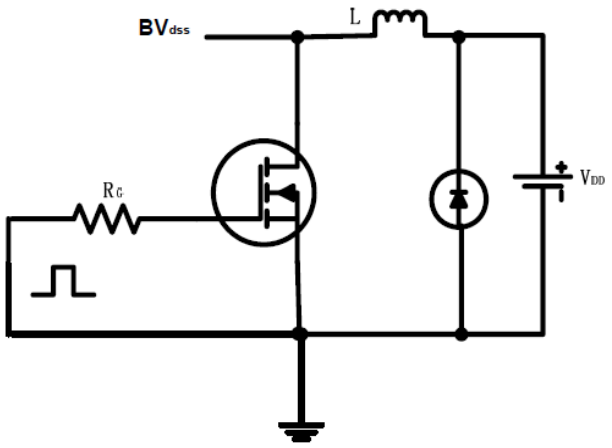


Figure 9: Breakdown Voltage Variatio With Temperature

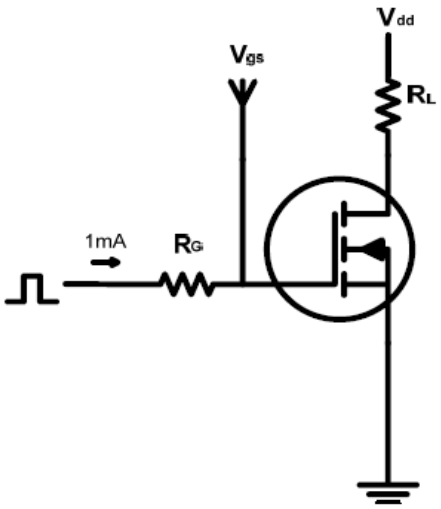


Test circuits and Waveforms

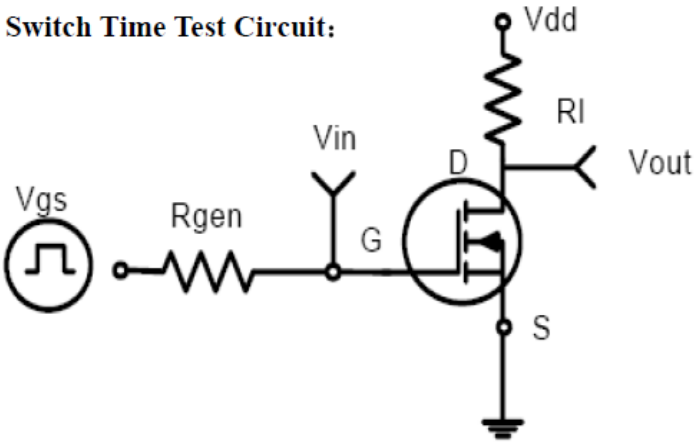
EAS test circuits:



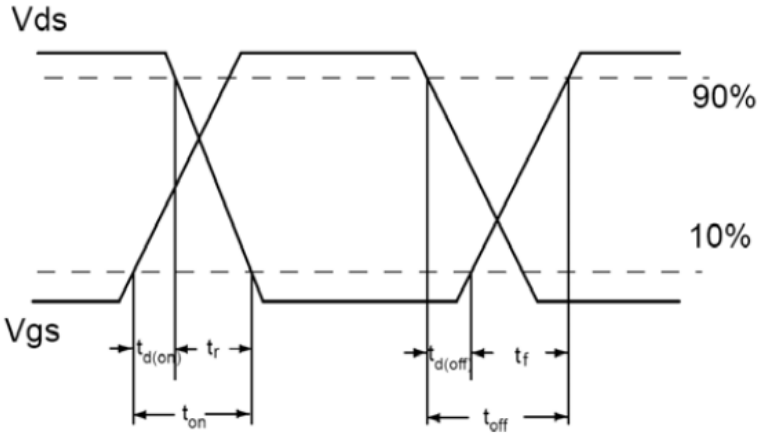
Gate charge test circuit:



Switch Time Test Circuit:

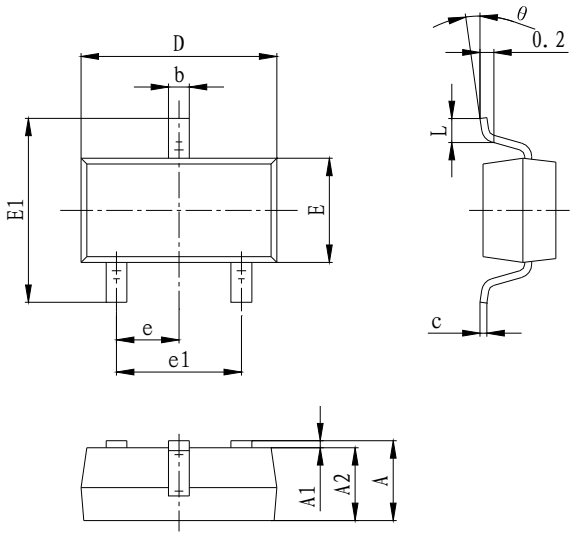


Switch Waveforms:



PACKAGE MECHANICAL DATA

SOT-23 Package Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°